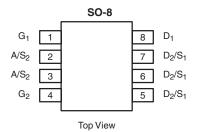




# Dual N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY						
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
Channel-1		$0.0185$ at $V_{GS} = 10 \text{ V}$	6.8	7.8		
Channel-1	30	0.0225 at V <sub>GS</sub> = 4.5 V 6.0	6.0	7.0		
Channel-2		0.0115 at V <sub>GS</sub> = 10 V	11.4	11.6		
Criailfiei-2		0.016 at V <sub>GS</sub> = 4.5 V	9.5	11.0		

SCHOTTKY PRODUCT SUMMARY					
V <sub>DS</sub> (V)	V <sub>SD</sub> (V) Diode Forward Voltage	I <sub>F</sub> (A)			
30	0.50 V at 1.0 A	2.0			



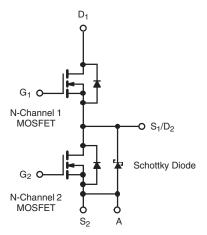
Ordering Information: Si4816BDY-T1-E3 (Lead (Pb)-free)

Si4816BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Available
- LITTLE FOOT<sup>®</sup> Plus Power MOSFET
- 100 % R<sub>g</sub> Tested





ABSOLUTE MAXIMUM RATI	<b>NGS</b> T <sub>A</sub> = 25	°C, unless	otherwise	noted			
			Channel-1		Channel-2		
Parameter	Symbol	10 s	Steady State	10 s	Steady State	Unit	
Drain-Source Voltage	$V_{DS}$		30				
Gate-Source Voltage	$V_{GS}$	V <sub>GS</sub> 20				- V	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C		6.8	5.8	11.4	8.2	
	T <sub>A</sub> = 70 °C	- I <sub>D</sub>	5.5	4.6	9.0	6.5	
Pulsed Drain Current		I <sub>DM</sub>	30		40		Α
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	1	0.9	2.2	1.15	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	10		20		
Avalanche Energy	L = 0.1 mm	E <sub>AS</sub>		5		20	mJ
	T <sub>A</sub> = 25 °C	В	1.4	1.0	2.4	1.25	14/
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	- P <sub>D</sub>	0.9	0.64	1.5	0.8	W
Operating Junction and Storage Temperatu	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS									
		Char	nel-1	Chan	nel-2	Scho	ottky		
Parameter	Symbol	Тур.	Max.	Тур.	Max.	Тур.	Max.	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	R <sub>thJA</sub>	72	90	43	53	48	60	
Maximum Junction-to-Ambient	Steady State	itnJA	100	125	82	100	80	100	°C/W
Maximum Junction-to-Foot (Drain) Steady State		R <sub>thJF</sub>	51	63	25	30	28	35	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

# Si4816BDY

# Vishay Siliconix



Parameter	Symbol Test Conditions				Typ. <sup>a</sup>	Max.	Unit	
Static						<u> </u>		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	Ch-1	1.0		3.0	V	
g	GO(III)	20 00, 5	Ch-2	1.0		3.0	-	
Gate-Body Leakage	$I_{GSS}$	$v_{\text{DQ}} = 0 \text{ V}$ , $v_{\text{DQ}} = 20 \text{ V}$	Ch-1			100	nA	
			Ch-2 Ch-1			100		
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	Ch-2			100		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V 22 V V 2 V T 25 22	Ch-1			15	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	Ch-2			2000		
On-State Drain Current <sup>b</sup>	ls.	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	Ch-1	20			Α	
On-State Drain Current	I <sub>D(on)</sub>		Ch-2	30				
		$V_{GS} = 10 \text{ V}, I_D = 6.8 \text{ A}$	Ch-1		0.0155	0.0185		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.4 A	Ch-2		0.0093	0.0115	Ω	
Diam-Source On-State nesistance	09(011)	$V_{GS} = 4.5 \text{ V}, I_D = 6.0 \text{ A}$	Ch-1		0.0185	0.0225	32	
		$V_{GS} = 4.5 \text{ V}, I_D = 9.5 \text{ A}$	Ch-2		0.013	0.016		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 6.8 \text{ A}$	Ch-1		30		S	
Forward fransconductance	91S	$V_{DS} = 15 \text{ V}, I_{D} = 11.4 \text{ A}$	Ch-2 Ch-1 Ch-2 Ch-1 Ch-2 Ch-1 Ch-2 Ch-1 Ch-2		31			
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	$I_{S} = 1 A, V_{GS} = 0 V$	Ch-1		0.73	1.1	V	
blode Forward Voltage		I <sub>S</sub> = 1 A, V <sub>GS</sub> = 0 V	Ch-2		0.47	0.5	v 	
Dynamic <sup>a</sup>								
Total Gate Charge	Qg	Channal 4	Ch-1		7.8	10		
Total Gate Offarge	y	Channel-1 $V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 6.8 \text{ A}$			11.6	18		
Gate-Source Charge	$Q_{qs}$	l l l l l l l l l l l l l l l l l l l	Ch-1		2.9		nC	
-		Channel-2	Ch-2		4.8 2.3			
Gate-Drain Charge	$Q_{gd}$	$V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = -11.4 \text{ A}$	Ch-1 Ch-2		3.7			
			Ch-1	1.5	3.0	4.5		
Gate Resistance	$R_{g}$		Ch-2	0.9	1.8	2.7	Ω	
Turn On Dolou Time	+		Ch-1		11	17		
Turn-On Delay Time	t <sub>d(on)</sub>	Channel-1	Ch-2		13	20		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 15 $\Omega$ $I_D \cong$ 1 A, $V_{GEN}$ = 10 V, $R_g$ = 6 $\Omega$	Ch-1		9	15		
The Thine	۲r		Ch-2		9	15		
Turn-Off Delay Time	t <sub>d(off)</sub>	Channel-2	Ch-1		24	40	ns	
-	t <sub>f</sub>	$V_{DD} = 15 \text{ V}, R_L = 15 \Omega$	Ch-2		31 9	50 15		
Fall Time		$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 6 \Omega$	Ch-1 Ch-2		11	17		
	t <sub>rr</sub>	I <sub>F</sub> = 1.3 A, dI/dt = 100 A/μs	Ch-1		20	35		
Source-Drain Reverse Recovery Time		$I_F = 2.2 \text{ A}, \text{ dI/dt} = 100 \mu\text{A}/\mu\text{s}$	Ch-2		20	00	-	

a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

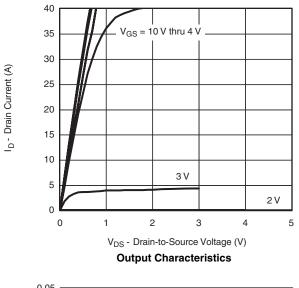


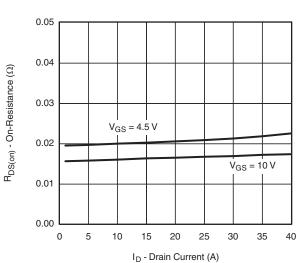


<b>SCHOTTKY SPECIFICATIONS</b> $T_J = 25$ °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Forward Voltage Drop	$V_F = I_F = 1.0 \text{ A}$ $I_F = 1.0 \text{ A}, T_J = 125$	I <sub>F</sub> = 1.0 A		0.47	0.50	V	
Forward voltage Drop		I <sub>F</sub> = 1.0 A, T <sub>J</sub> = 125 °C		0.36	0.42		
	I <sub>rm</sub>	V <sub>R</sub> = 30 V		0.004	0.100		
Maximum Reverse Leakage Current		$V_R = 30 \text{ V}, T_J = 100 ^{\circ}\text{C}$		0.7	10	mA	
		V <sub>R</sub> = - 30 V, T <sub>J</sub> = 125 °C		3.0	20	ľ	
Junction Capacitance	C <sub>T</sub>	V <sub>R</sub> = 10 V		50		pF	

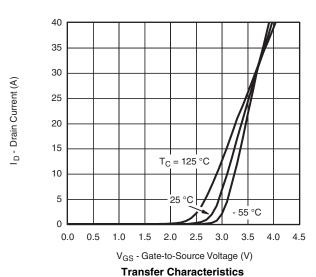
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

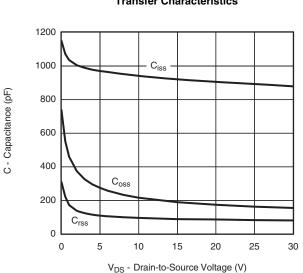
### CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





On-Resistance vs. Drain Current



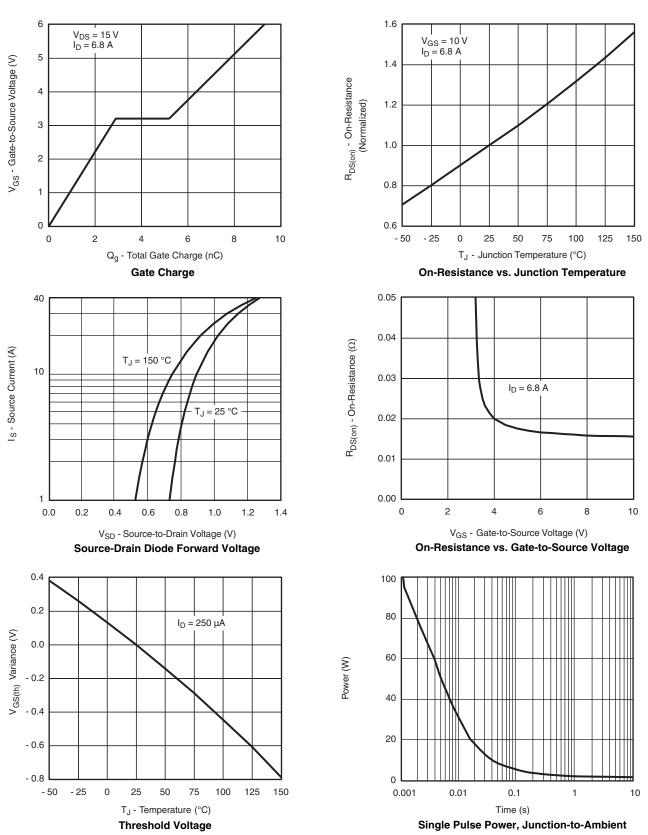


Capacitance

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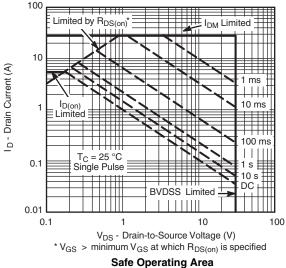
# VISHAY.

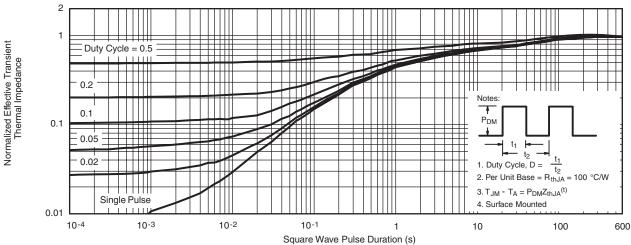
### CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



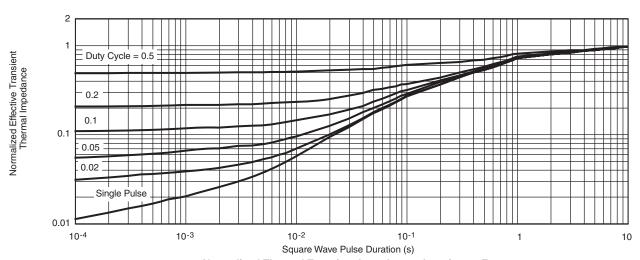


### CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Normalized Thermal Transient Impedance, Junction-to-Ambient

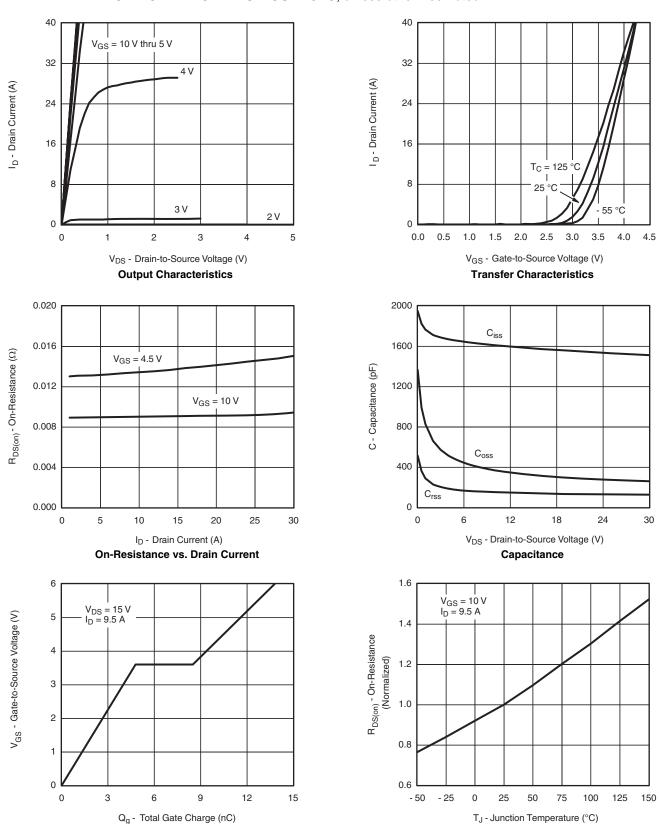


Normalized Thermal Transient Impedance, Junction-to-Foot

## Vishay Siliconix

# VISHAY.

### CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

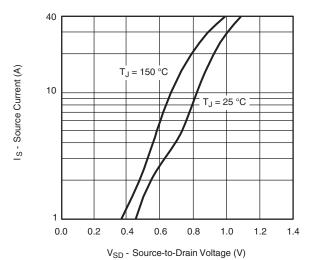


**Gate Charge** 

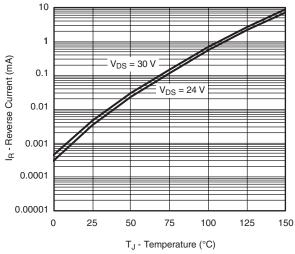
On-Resistance vs. Junction Temperature



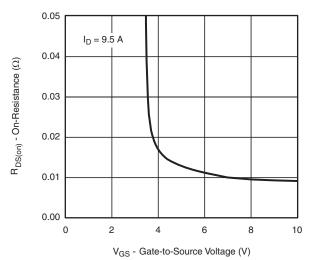
### **CHANNEL-2 TYPICAL CHARACTERISTICS** 25 $^{\circ}$ C, unless otherwise noted



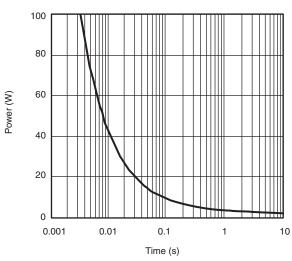
Source-Drain Diode Forward Voltage



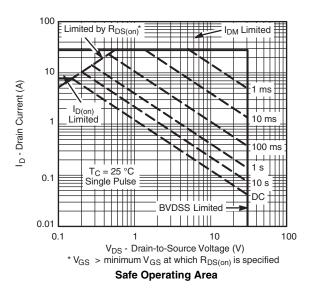
**Reverse Current vs. Junction Temperature** 



On-Resistance vs. Gate-to-Source Voltage



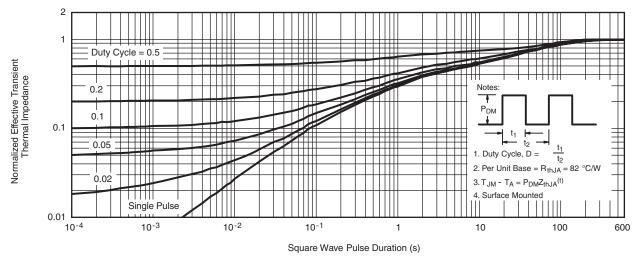
Single Pulse Power, Junction-to-Ambient



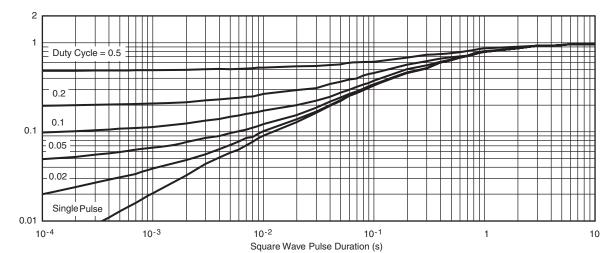
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### CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



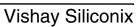
#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

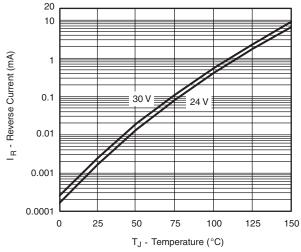
Normalized Effective Transient Thermal Impedance



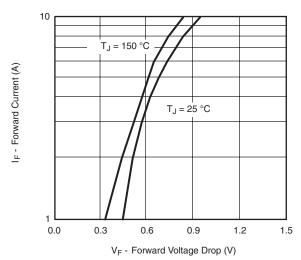




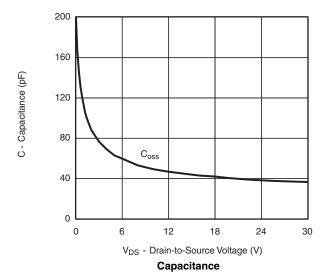
### SCHOTTKY TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







**Forward Voltage Drop** 



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?73026.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	) BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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